SD5210G4

Intel Gen 10th 10 Cores Xeon, i9 CPU w/ 10 x GbE (Optional 8 x PoE)/ 3 x COM/ 3 x DP/ 2 x HDMI/ 4 x USB 3.2 Gen 1/ NVIDIA® GeForce GTX 1060 GPU/ 9-48V Input AI GPU Computing

Features

- **Intel GEN 10th 10 Cores Xeon W-1290TE / i9-10900TE**
- **NVIDIA® GeForce GTX 1060 GPU**
- **Support 1280 CUDA Cores**
- **8 x DI, and 4 x DO and 3 x RS-232/422/485**
- **1 x M.2 B key, 1 x M.2 A-E key & 3 x MiniPCIe expansion slots**
- **Dual Hot Swappable SATA Storage RAID 0,1,5**
- **9-48V DC Input and Operating Temp.: -40~70°C**
- **10 x GbE RJ45 (Optional 8 x PoE and 8 x M12 X coded connectors)**

Specifications

System	
CPU	Intel Gen10 Xeon W-1290TE (20M Cache 2.0GHz up to 4.6GHz)*
	Intel Gen10 Core i9-10900TE (20M Cache 2.0GHz up to 4.5GHz)
	Intel Gen10 Core i7-10700TE (16M Cache 2.0GHz up to 4.4GHz)
	Intel Gen10 Core i5-10500TE (12M Cache 2.3GHz up to 3.7GHz)
	Intel Gen10 Core i3-10100TE (6M Cache 2.3GHz up to 3.6GHz)
	Intel Gen10 Core G5900TE (4M Cache 3.0GHz)
	* Use only with Intel W480E
Chipset	Q470E / W480E
Memory	2 x DDR4 2666/2933 MHz SO-DIMM up to 64GB
LAN Chipset	9 x Intel i210-AT and 1 x i219LM (support iAMT) Gb/s Ethernet Controllers Onboard Support PXE and WOL
Watchdog	1 ~ 255 Level Reset
TPM	2.0

I/O	
Serial Port	3 x RS 232/422/485 (option additional 1 x RS 232/422/485)
USB Port	4 x USB 3.2 Gen 1 Ports
LAN	10 x RJ45 Ports for GbE (Optional 8 with M12 X coded connectors and 8 x POE total Max.120W)
Video Port	3 x DP, 2 x HDMI Ports
DIO Port	8 xDI (5~48VDC) and 4 x DO (5VDC, 100mA)
Audio	1 x Line-out, 1 x Line-in and 1 x Mic-in
Expansion Bus	2 x Full Mini-PCIe Slots, 1 x Mini-PCIe w/ USB interface only for LTE sharing 2 x SIM Card Sockets with M.2 B Key 3042 slot
	1x M.2 A-E Key 2230 slot, 1 x M.2 B Key 3042 slot w/ 2 x SIM Card Sockets for LTE

Storage	
Type	2 x 2.5" Drive Bay for SATA Type HDD/SSD RAID 0, 1, 5
	1 x M.2 M key 2280 slot supports NVMe and SATA SSD * Thermal heatsink is required for M.2 storage. Please contact sales for more information.

Graphics	
MXM Graphics	NVIDIA® GeForce GTX 1060 GPU (1280 CUDA Cores) w/6GB GDDR5
	Max Resolution (HDMI 2.0b) : 4096 x 2160 @ 60Hz
Built-in Graphics	Intel UHD Graphics 630
	Max Resolution (DP 1.2) : 4096 x 2340 @ 60Hz

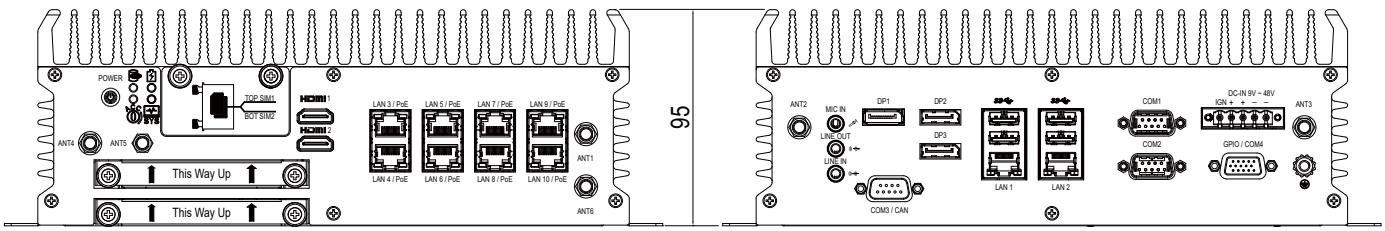
Environmental	
Operating Temp.	-40°C ~ 60°C w/ GTX 1060 w/0.6 m/S airflow
Storage Temp.	-40°C ~ 80°C
Relative Humidity	10% RH – 90% RH (non-condensing)
Vibration (with SSD)	IEC60068-2-64, random, 2.5G@5~500Hz, 1hr/axis
	MIL-STD-810G, Method 514.6, Procedure I, Cat.4, Operating
Shock	Operating: MIL-STD-810G, Method 516.6, Procedure I, Trucks and semi-trailers=15G (11ms) with SSD
Certifications	CE, FCC Class A, E13, EN50155

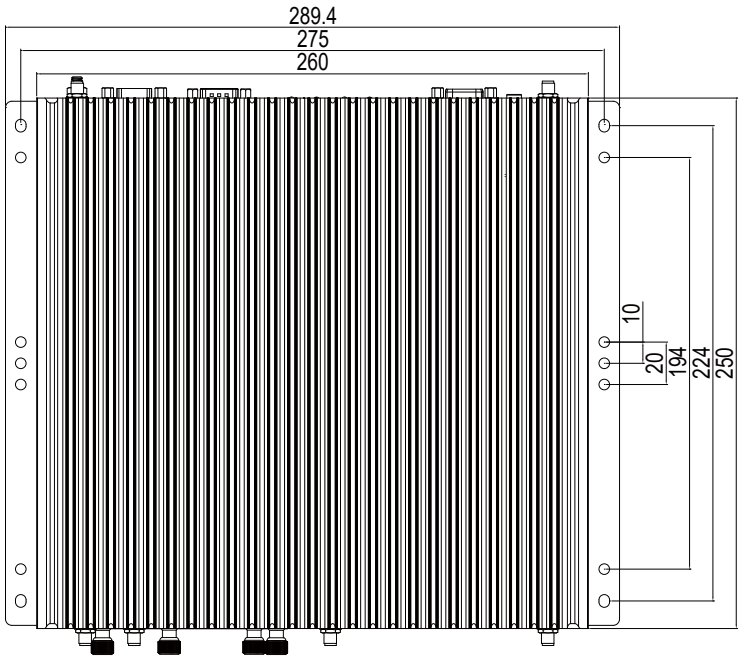
Power Requirement	
Power Input	9V - 48V DC Power Input
Power Protection	Automatics Recovery Short Circuit Protection
Power Mgmt.	Vehicle Power Ignition for Variety Vehicle
Power Off Control	Power off Delay Time Setting by BIOS and Software
Battery Backup (Option)	Internal Battery Kit for 10 Mins Operating (Operating Temp. -20 ~ 60°C)

Mechanical	
Construction	Aluminum Alloy
Mounting	Wall-mount
Weight	5300g (Barebone)
Dimensions	260(L) x 250(W) x 95(H) mm

Dimensions

Unit : mm





Ordering Information

Part Number	SD5210PXX-YY (P = PoE function; XX= G4 (w/GTX1060); YY= Z1,i9, i7, i5, i3 or C1)
Description	Intel Gen 10th 10 Cores Xeon, i9 CPU w/ 10 x GbE (Optional 8 x PoE)/3 x COM/ 3 x DP/ 2 x HDMI/4 x USB 3.2 Gen 1/ NVIDIA® GeForce GTX 1060 GPU/ 9-48V Input AI GPU Computing
State of Origin	Made in China

Optional Accessories

DRAM	DDR4-2933 MHz SO-DIMM, 4GB~32GB, 0~70°C/-40~85°C
SSD	M.2 2280 B-M key NVMe TLC -40~85°C 64GB~1TB w/ Heatsink
	M.2 2280 B-M key SATA TLC -40~85°C 64GB~1TB w/ Heatsink
	2.5 inch SATA TLC -40~85°C 64GB~2TB
Wifi	M.2 2230 A-E key 802.3 a/b/g/n/ac
Modem	M.2 3042 B key LTE module
GPS	MiniPCIe GPS module
CANBUS	MiniPCIe CANBUS module
Battery backup kit	Battery Kit, 5200m/h, -30~60°C, discharge -20~60°C, operating about 10 mins
Power adapter	AC/DC 220W/24V or 280W/24V power adapter